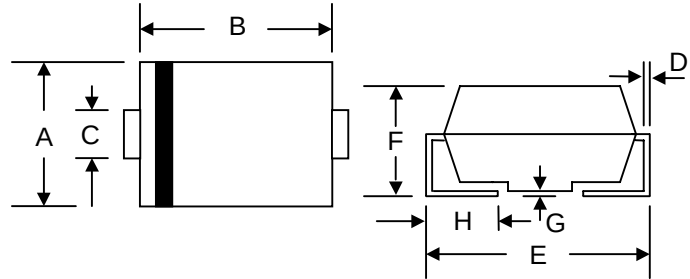


Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 80 A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O



Mechanical Data

- Case: SMC/DO-214AB, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.20 grams (approx.)
- **Lead Free: For RoHS / Lead Free Version**

SMC/DO-214AB		
Dim	Min	Max
A	5.59	6.22
B	6.60	7.11
C	2.75	3.25
D	0.152	0.305
E	7.75	8.13
F	2.00	2.62
G	0.051	0.203
H	0.76	1.27
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Characteristic	Symbol	30BQ 020	30BQ 030	30BQ 040	30BQ 050	30BQ 060	30BQ 080	30BQ 100	30BQ 150	30BQ 200	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	80	100	150	200	V
RMS Reverse Voltage	V _R (RMS)	14	21	28	35	42	56	70	105	140	V
Average Rectified Output Current @T _L = 75°C (Note 1)	I _O	3.0									A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	80									A
Forward Voltage @I _F = 3.0A	V _{FM}	0.55			0.75		0.85		0.92		V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	0.2 20									mA
Typical Junction Capacitance (Note 2)	C _j	250									pF
Typical Thermal Resistance (Note 1)	R θJA	20									°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150									°C

Note: 1. Mounted on P.C. Board with 5.0mm² copper pad area.

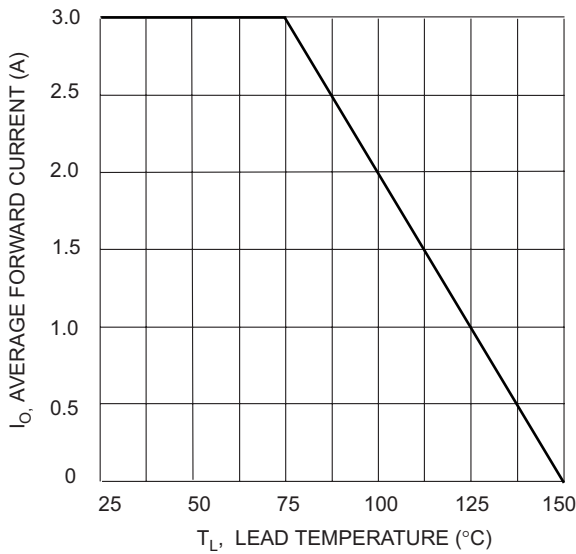


Fig. 1 Forward Current Derating Curve

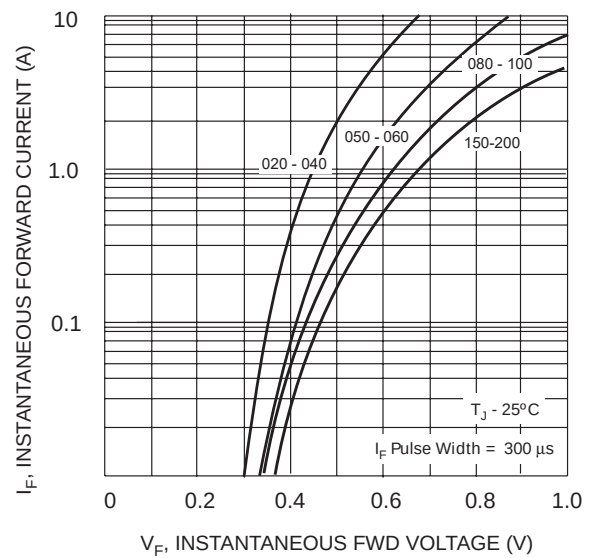


Fig. 2 Typ. Forward Characteristics

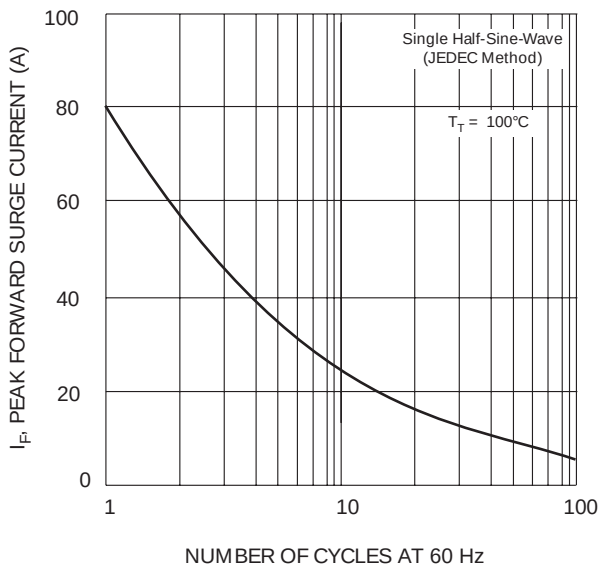


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

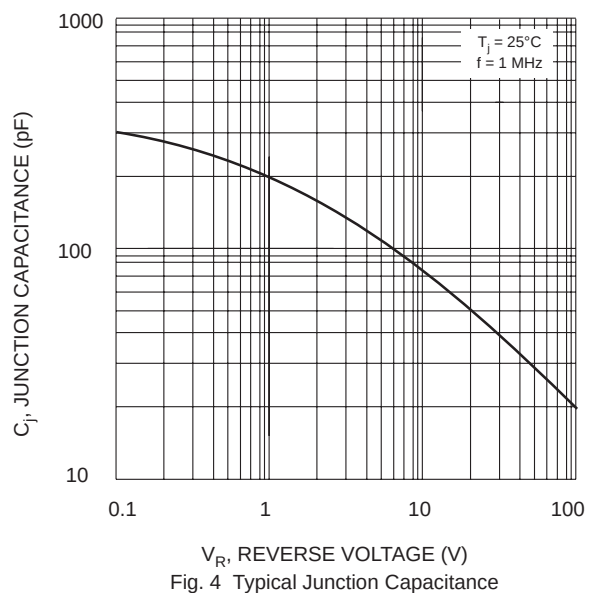


Fig. 4 Typical Junction Capacitance

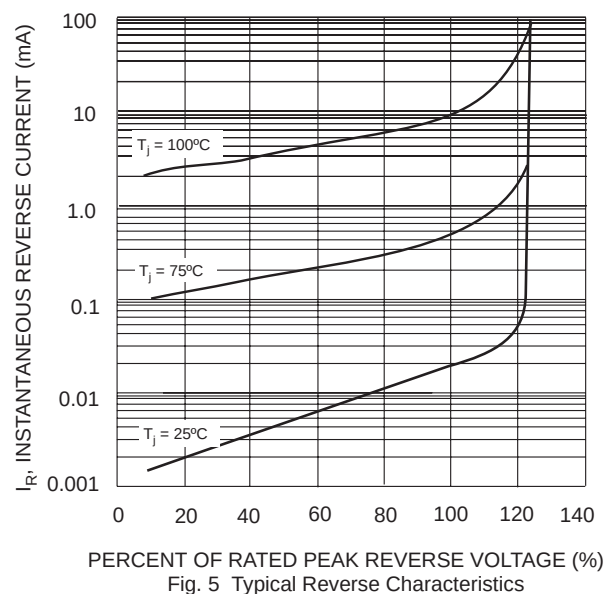


Fig. 5 Typical Reverse Characteristics